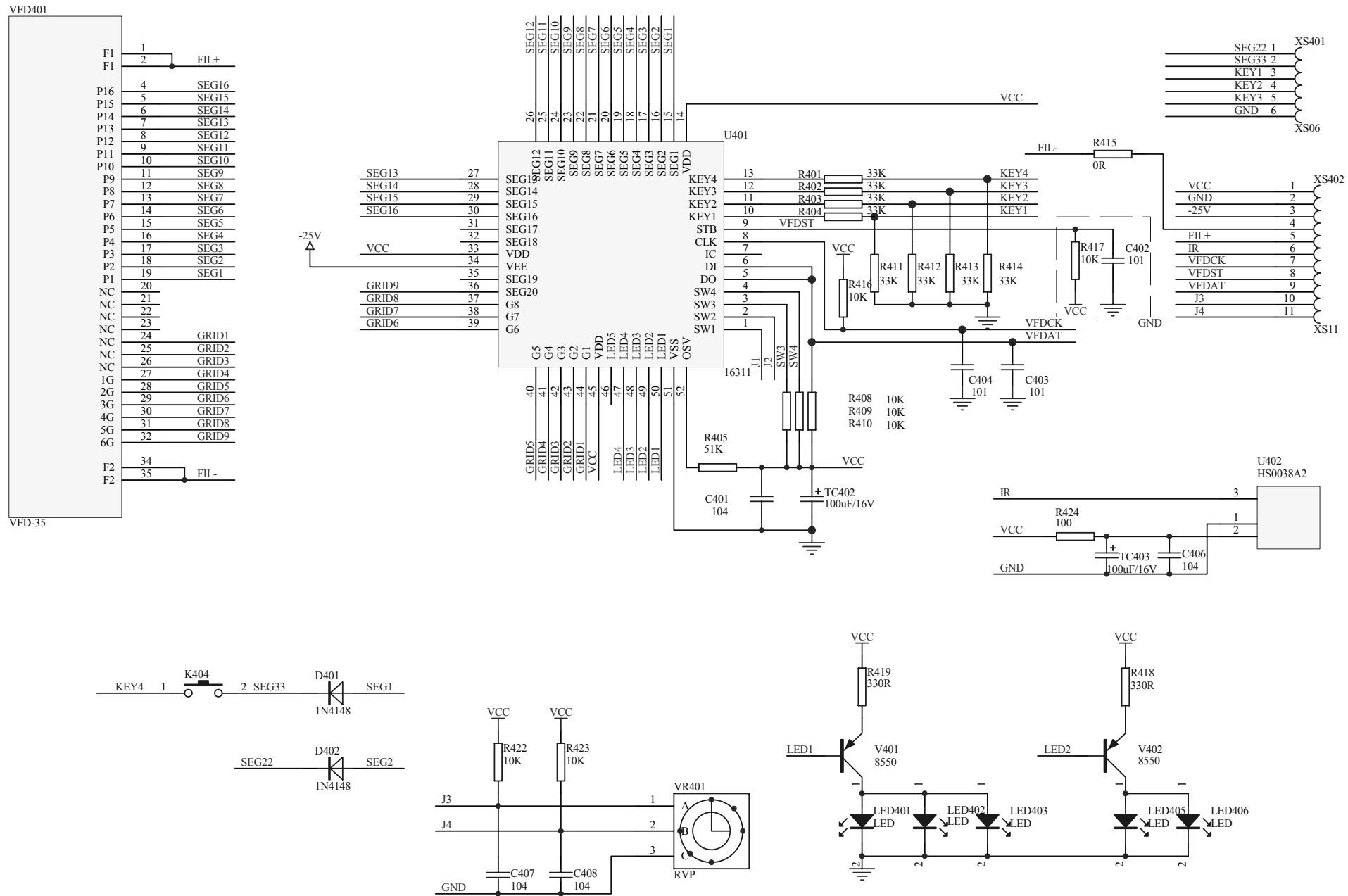
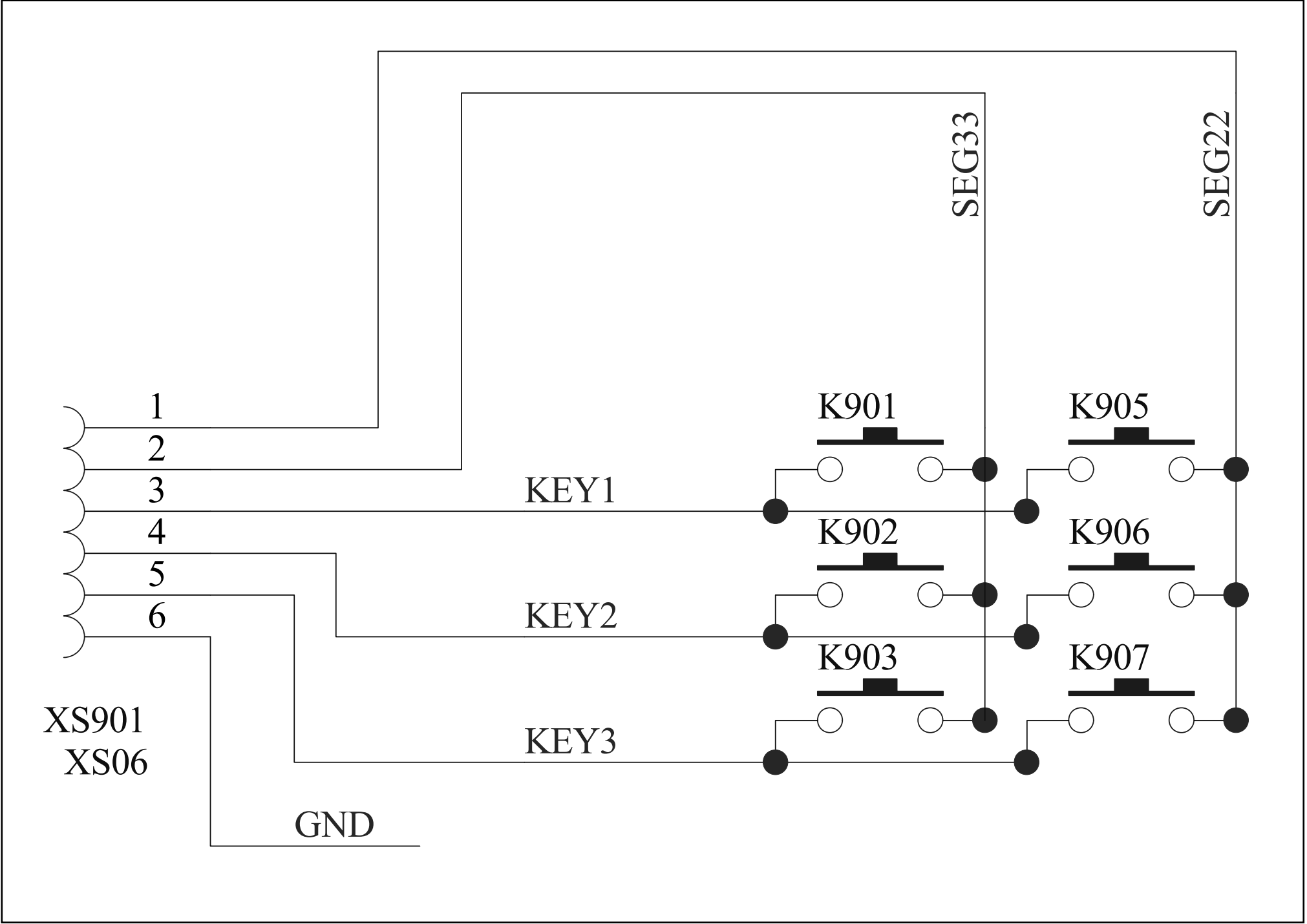
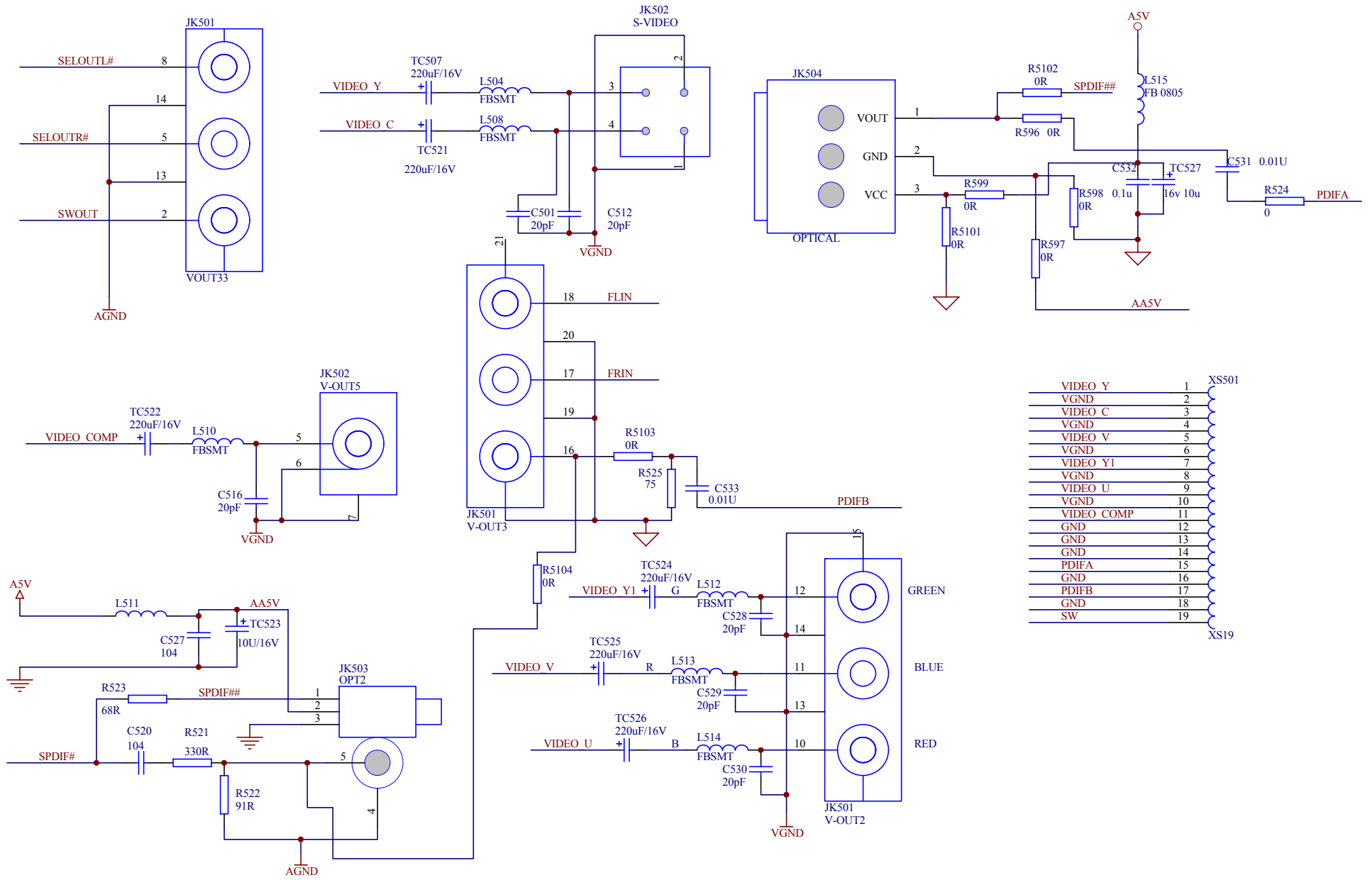


9. SCHEMATIC & P.C.B WIRING DIAGRAM
FRONT SCHEMATIC DIAGRAM



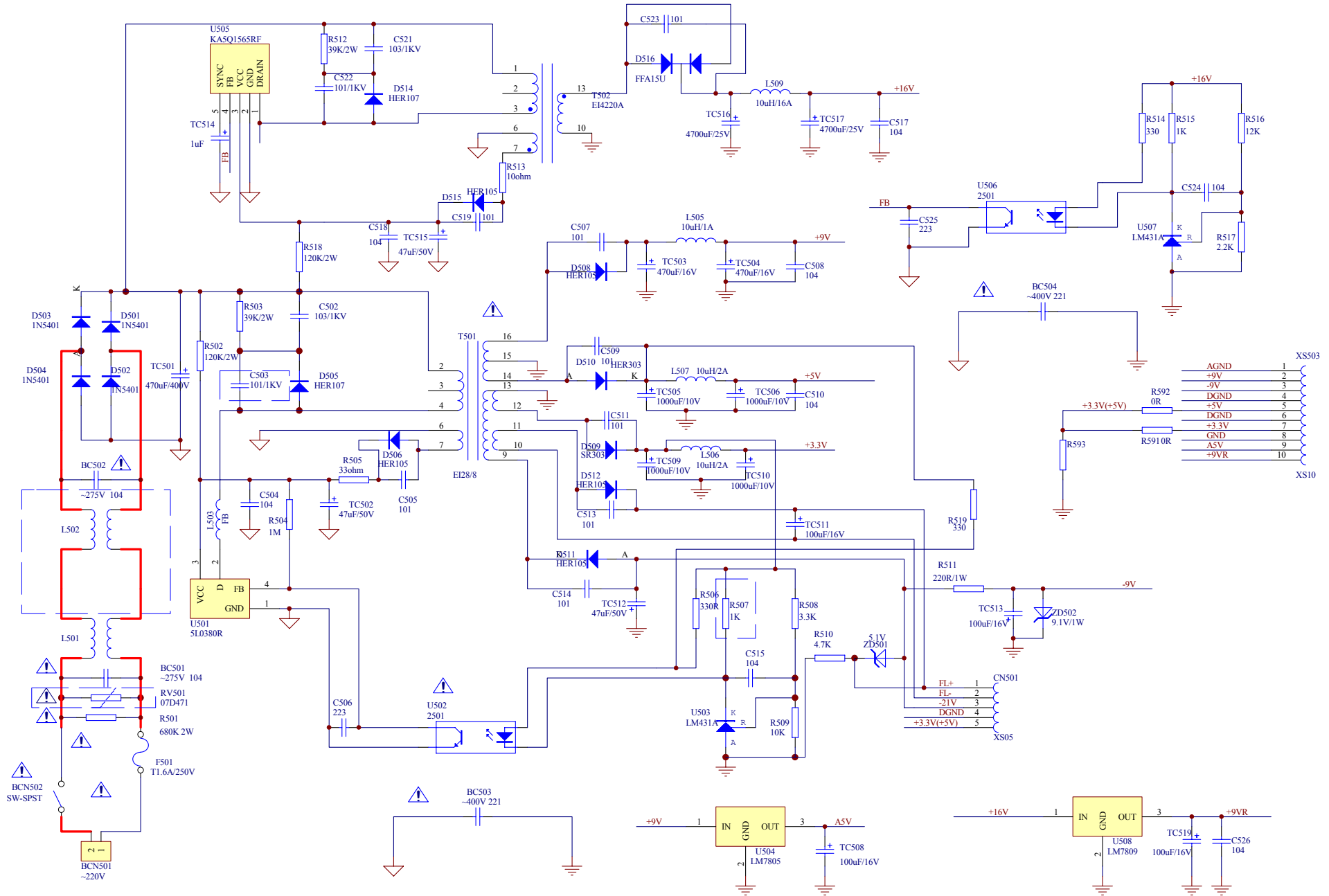
52

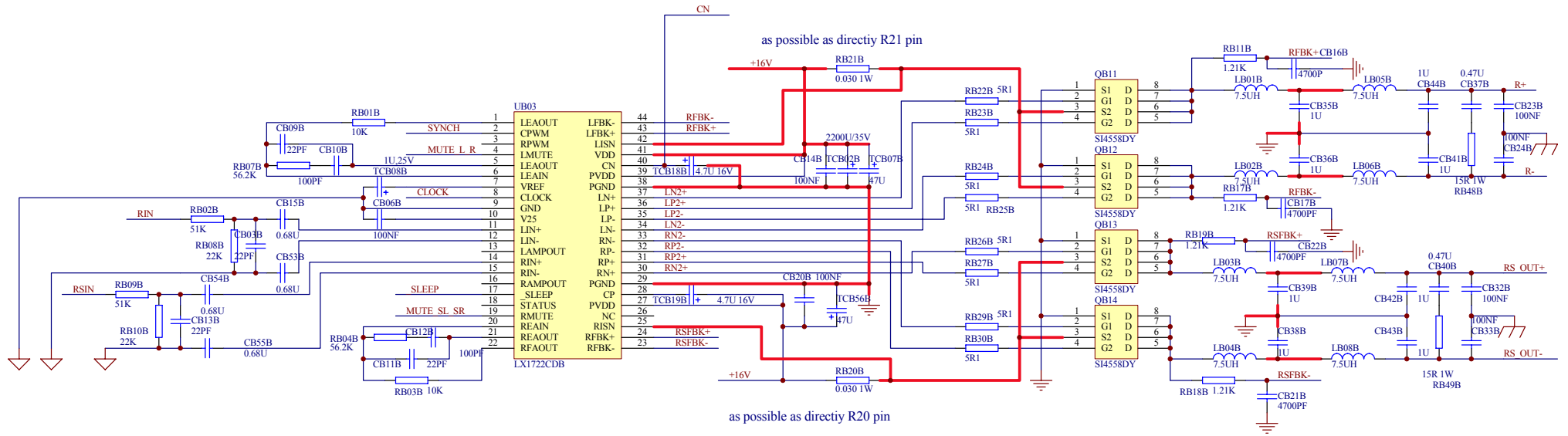




VIDEO Y	1
VGND	2
VIDEO C	3
VGND	4
VIDEO V	5
VGND	6
VIDEO Y1	7
VGND	8
VIDEO U	9
VGND	10
VIDEO COMP	11
GND	12
GND	13
GND	14
PDIFA	15
GND	16
PDIFB	17
GND	18
SW	19

POWER SOURCE/AMPLIFIER BOARD SCHEMATIC DIAGRAM

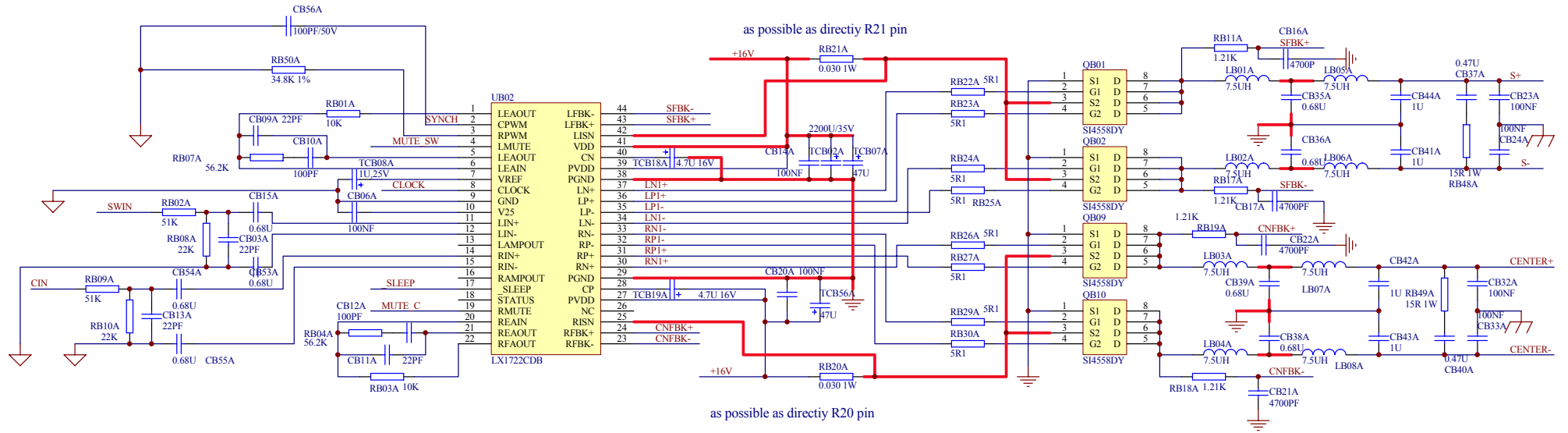




NOTE:

1. AGND and GND plate is expected, they are divided by the center of LX1721.
2. Red heavy line means needing heavy duty trace or copper.
3. Heat sink need to be solder on the AGND plate.
4. LPWM+, LPWM-, RPWM+, RPWM- must be kept as short as possible
5. Chassis gnd circles the whole board on both top and bottom layer.

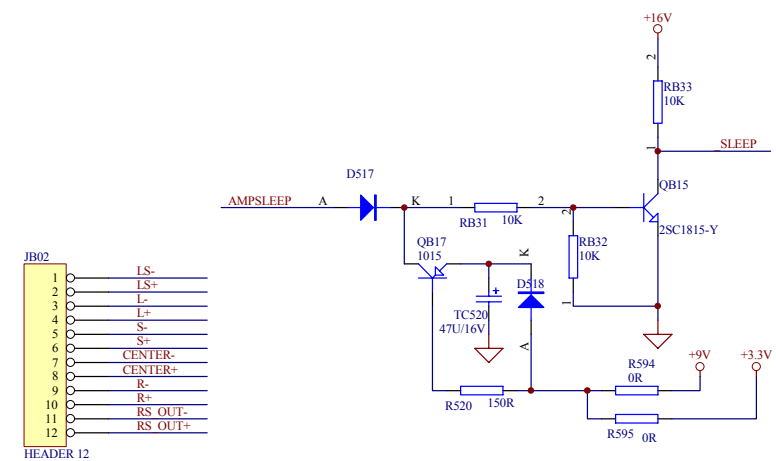
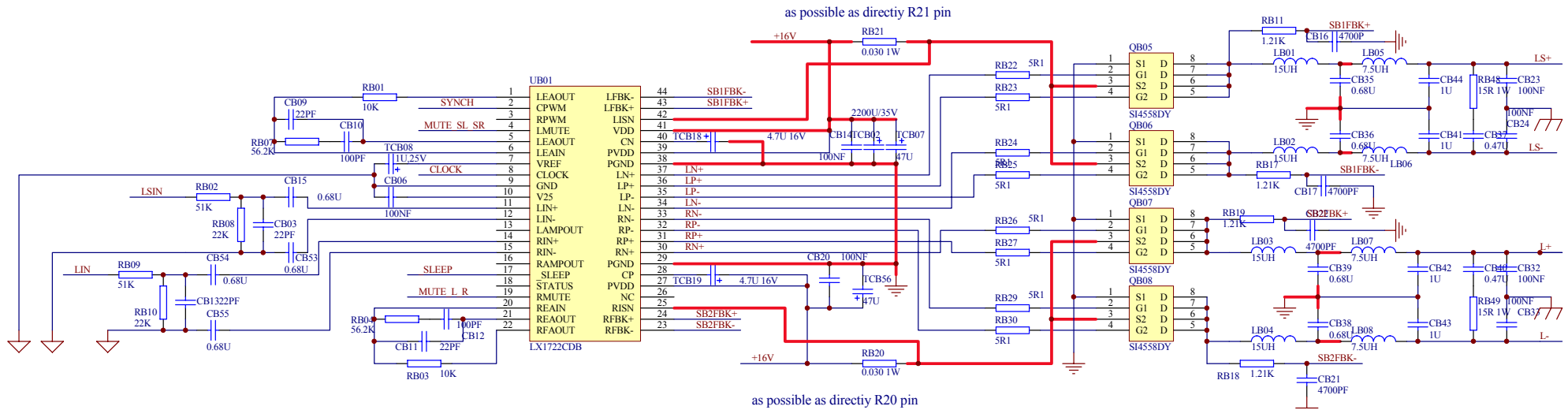
LN+, LP+, LP-, LN-, RN-, RP-, RP+, RN+, keep as short as possible



NOTE:

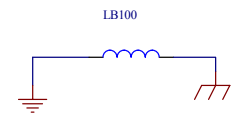
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2. Red heavy line means needing heavy duty trace or copper.
3. Heat sink need to be solder on the AGND plate.
4. LPWM+, LPWM-, RPWM+, RPWM- must be kept as short as possible
5. Chassis gnd circles the whole board on both top and bottom layer.

LN+, LP+, LP-, LN-RN-, RP-RP+, RN+, keep as short as possible

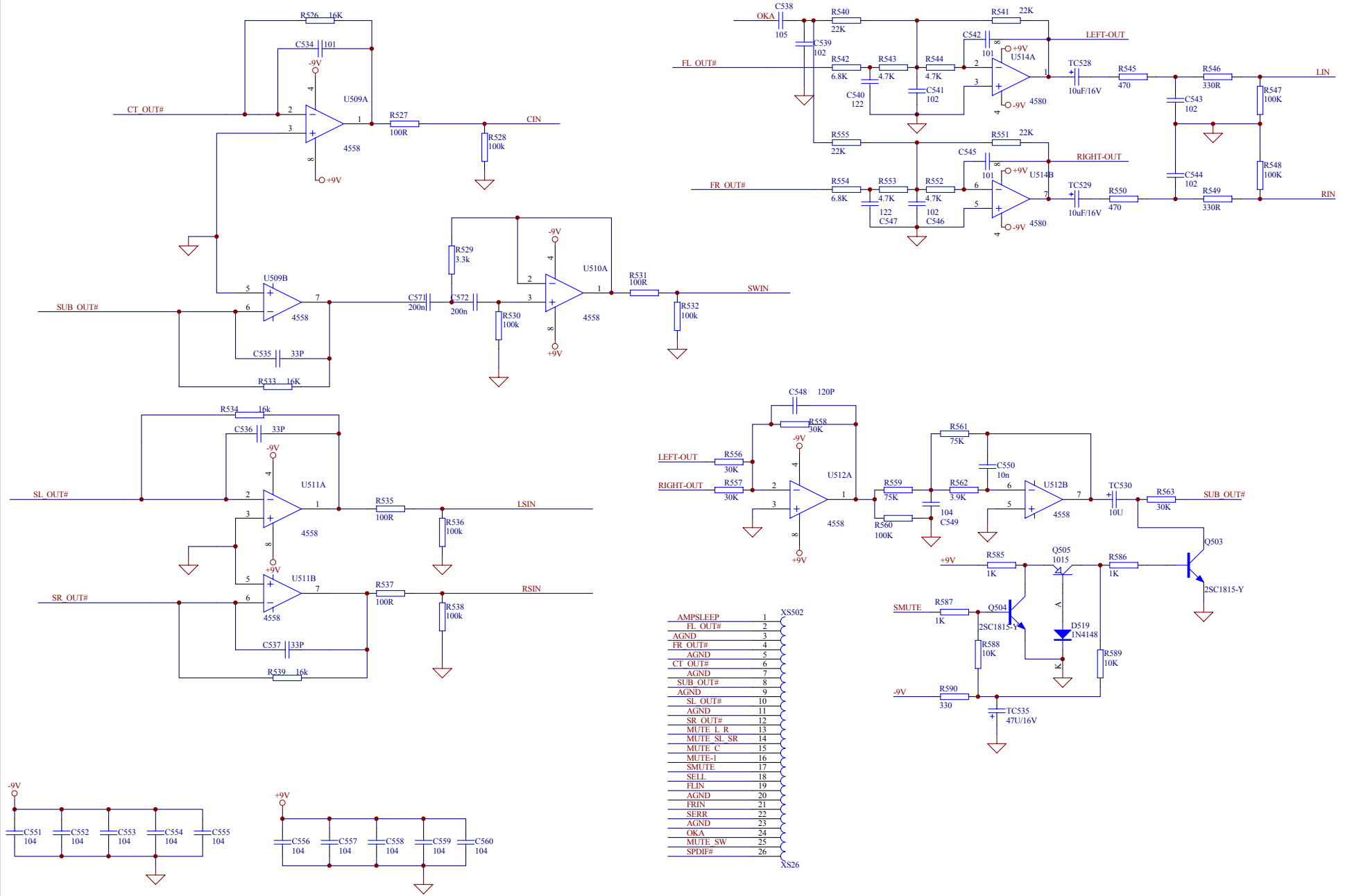


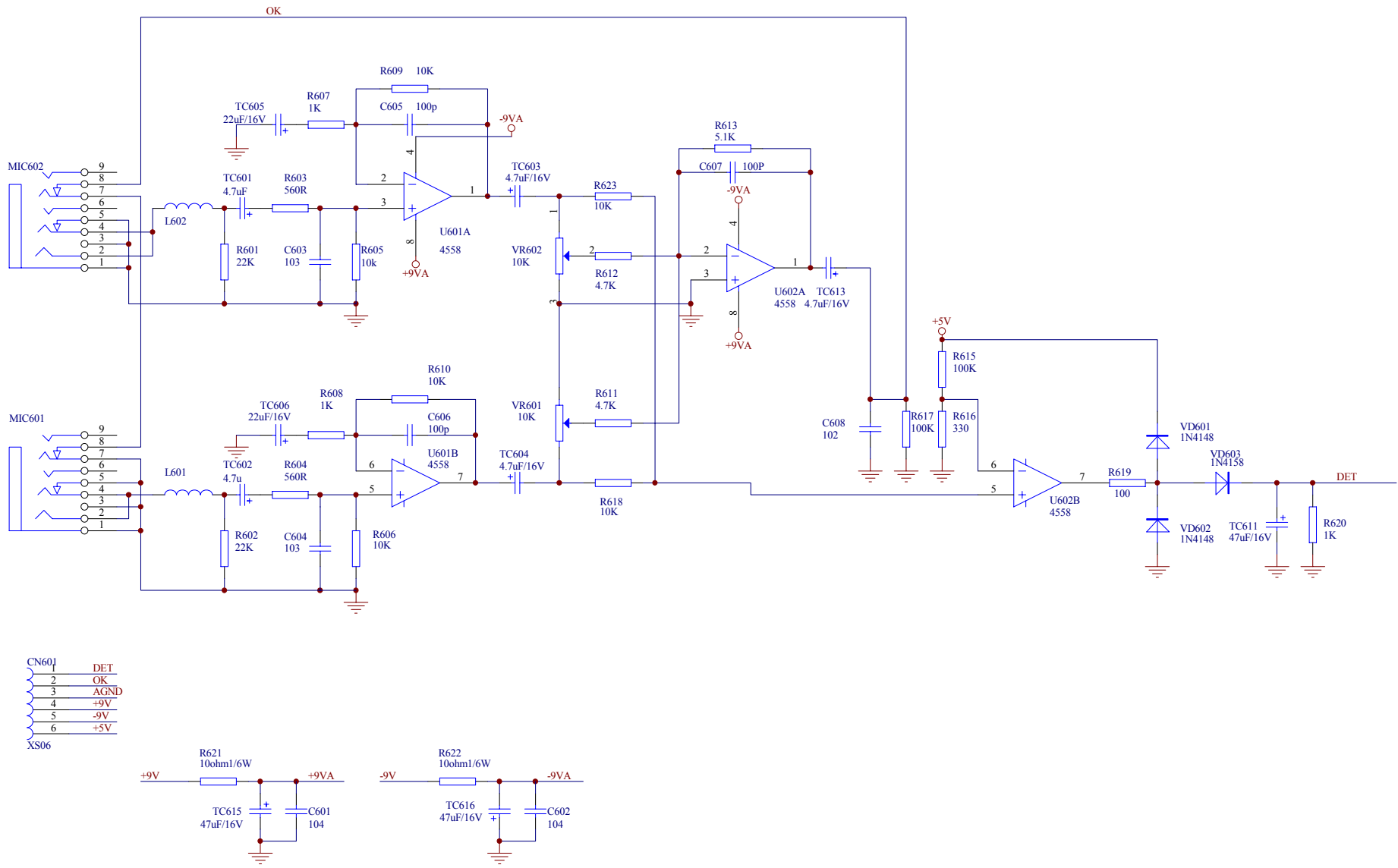
- NOTE:
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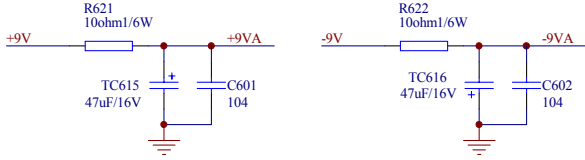


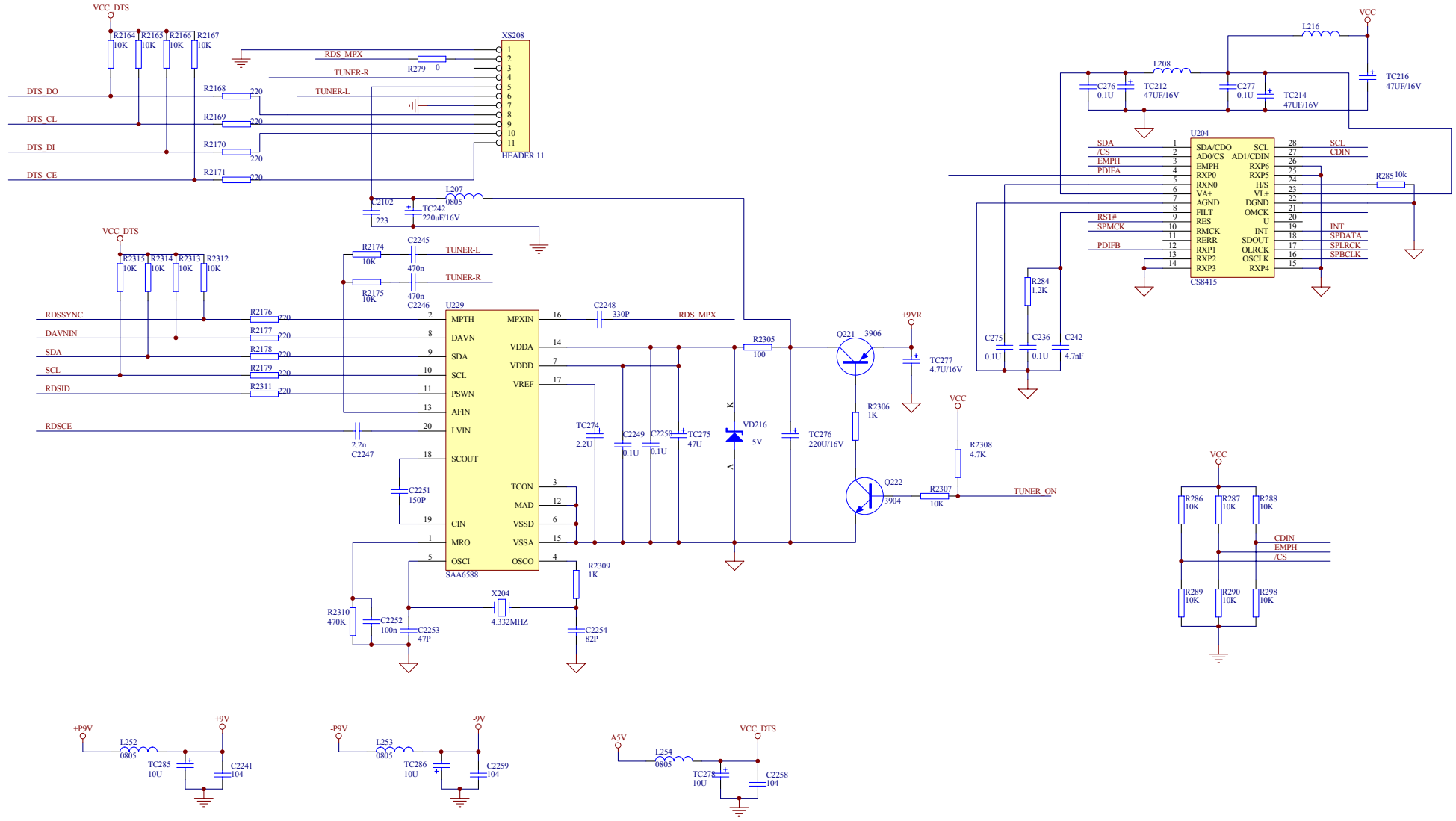
POWER SOURCE/AMPLIFIER BOARD SCHEMATIC DIAGRAM

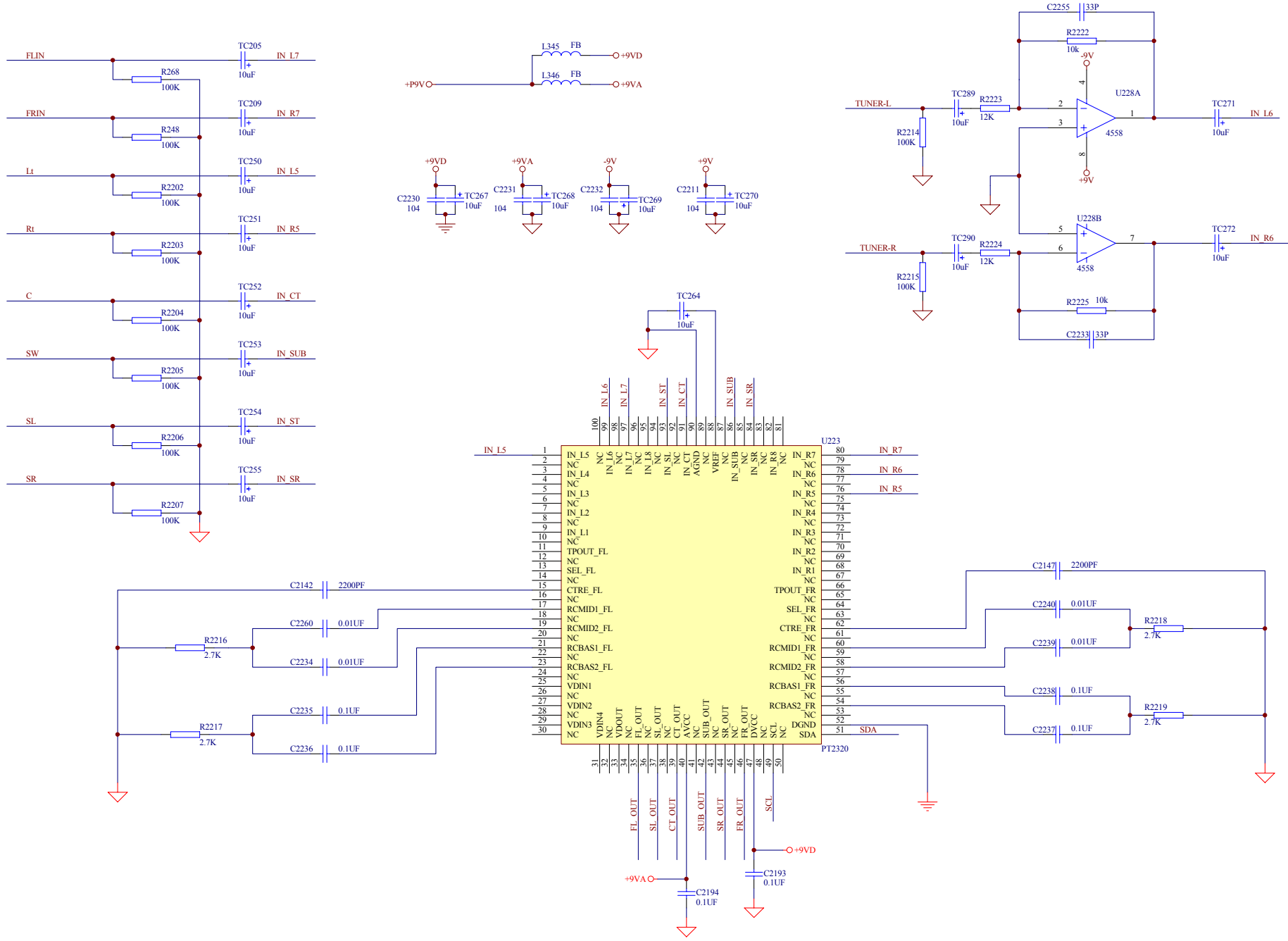


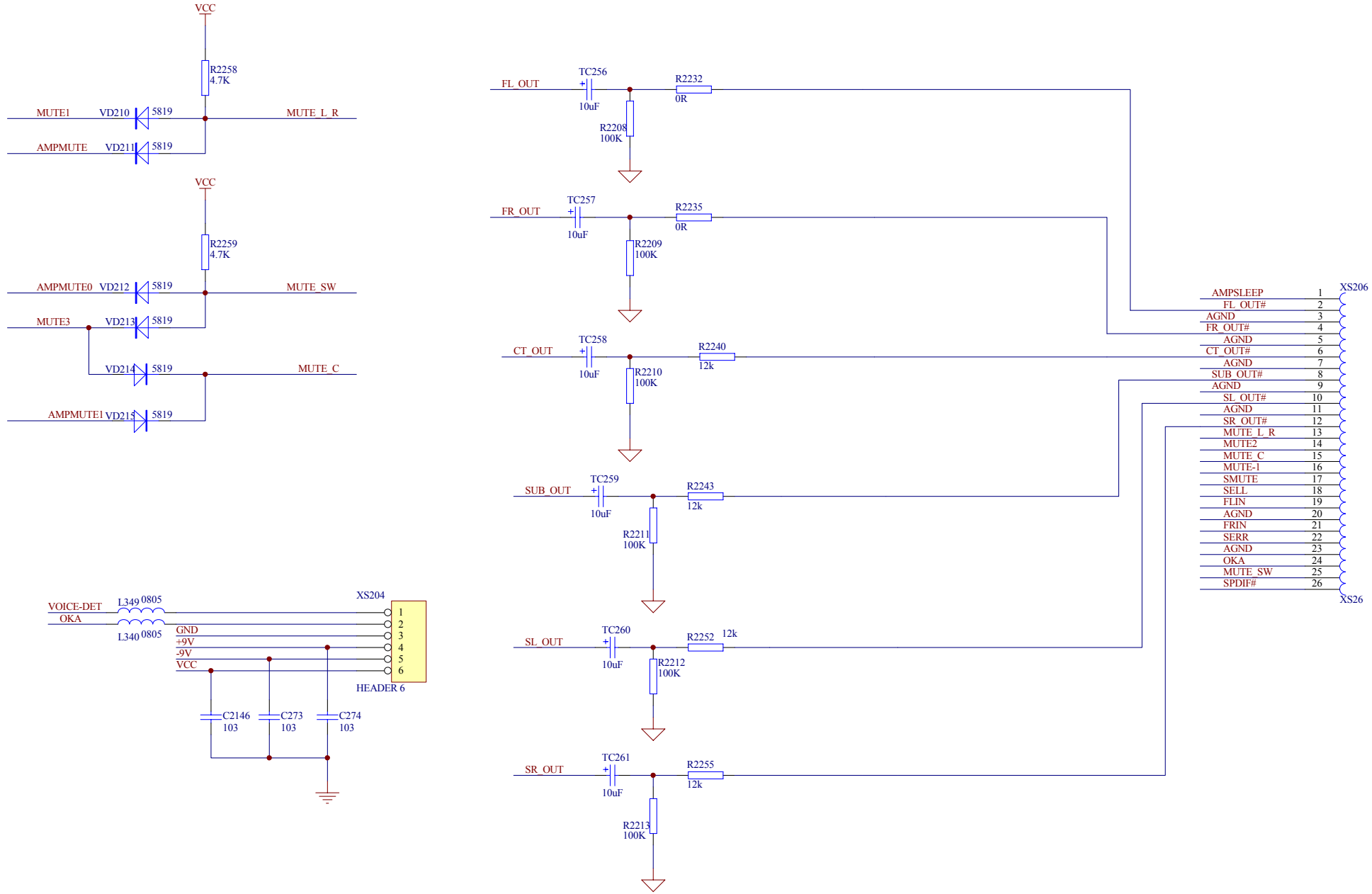


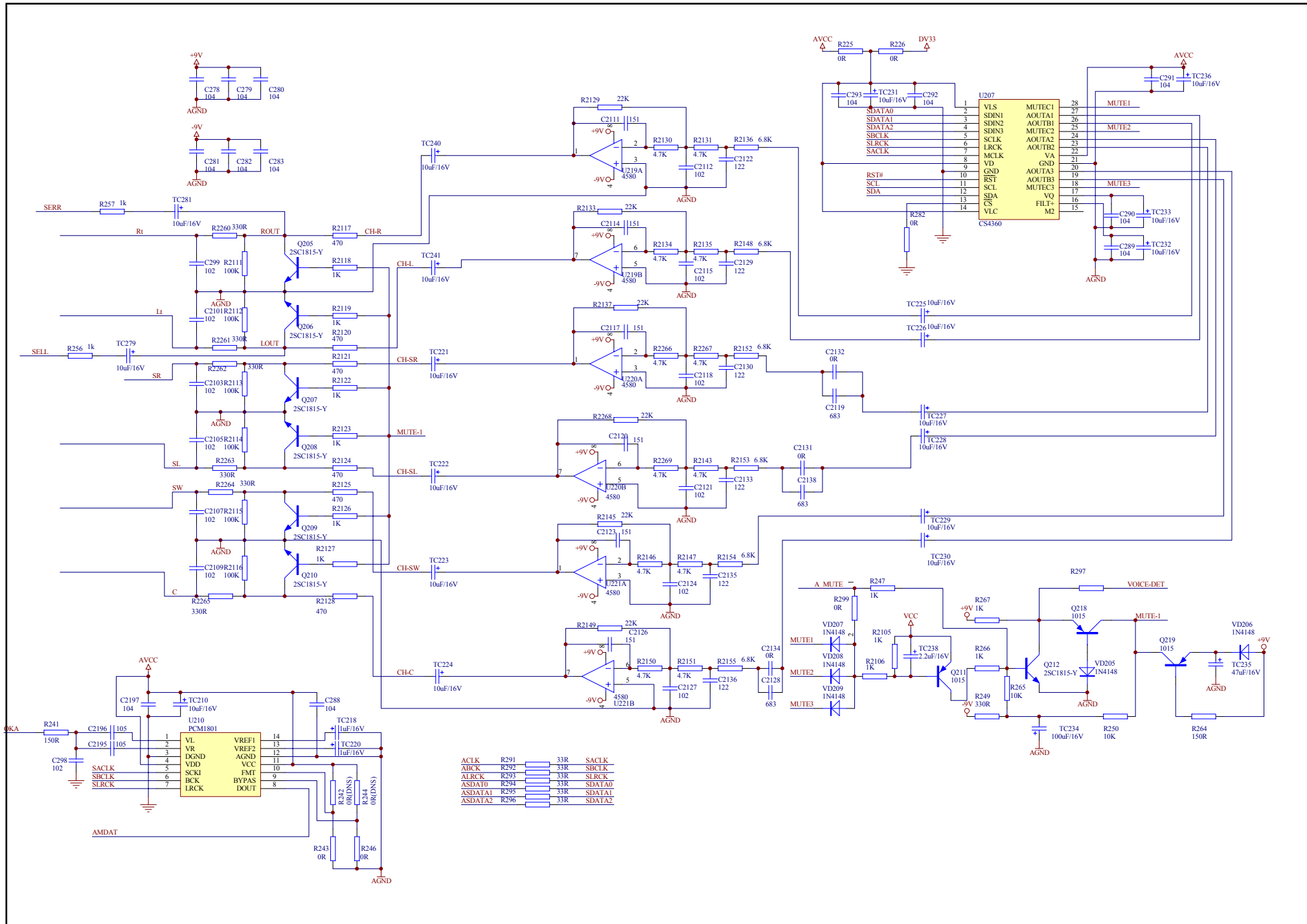
CN601	DET
1	OK
2	AGND
3	+9V
4	-9V
5	+5V
6	
XS06	











ACLK	R291	33R	SACLK
ABCK	R292	33R	SBCLK
ALRCK	R293	33R	SLRCK
ASDATA0	R294	33R	SDATA0
ASDATA1	R295	33R	SDATA1
ASDATA2	R296	33R	SDATA2

